

room temperature (e.g. 25 degrees Centigradee.g., 25 degrees Centigrade). To that end, bridge supports 12, bridge 14, and/or stage support 16 may be fabricated from one or more of the following materials: silicon carbide, iron alloys available under the trade name INVAR®, or name SUPER INVAR™, and/or ceramics, including but not limited to ZERODUR® ceramic. Coupled to bridge 14 is an imprint head 18, which extends from bridge 14 toward stage support 16. Disposed upon stage support 16 to face imprint head 18 is a motion stage 20. Motion stage 20 is configured to move with respect to stage support 16 along X and Y axes, but may move along the Z axis, as well. A radiation source 22 is coupled to system 10 to impinge actinic radiation upon motion stage 20. As shown, radiation source 22 is coupled to bridge 14 and includes a power generator 23 connected to radiation source 22. The components of system 10 are supported by table 24 that may be constructed to isolate the components of system 10 from vibrations in the surrounding environment. An exemplary table 24 is available from Newport Corporation of Irvine, California.

Please replace paragraph [0028] on page 9 with the following amended paragraph:

*S.S.  
12/6/07*  
<sup>28</sup> [0028] The present invention attenuates, if not abrogates, magnification/run out errors by providing control of the relative dimensions between the original pattern and the region of wafer upon which the original pattern is to be recorded. Specifically, the present invention allows control of the dimensional relations between the original pattern present in mold 28 and the recorded pattern formed on wafer 30. In this manner, the size of the recorded patterned-pattern may appear to be magnified and/or reduced, when compared to the original pattern. This may be